



**K8LPF1**

chip dimensions: 210 x 110 mils  
substrate: 5 mil thick Alumina  
metalization: WTi with 200u" Au for wire bonding  
resistors: TaN, 50 Ohms/square  
vias: 3 mil diameter, plated-thru  
layers:

chip outline = cyan  
top metal = black  
backside metal = blue  
vias = green  
resistors = red

*NATIONAL RADIO ASTRONOMY OBSERVATORY*

1180 Boxwood Estate Rd, Charlottesville, VA, 22903

NAME: k8lpf1

FILE: k8lpf1.dwg

DATE: 11/27/2007

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